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(54) Title: PACKAGED SURFACE ACOUSTIC WAVE DEVICES

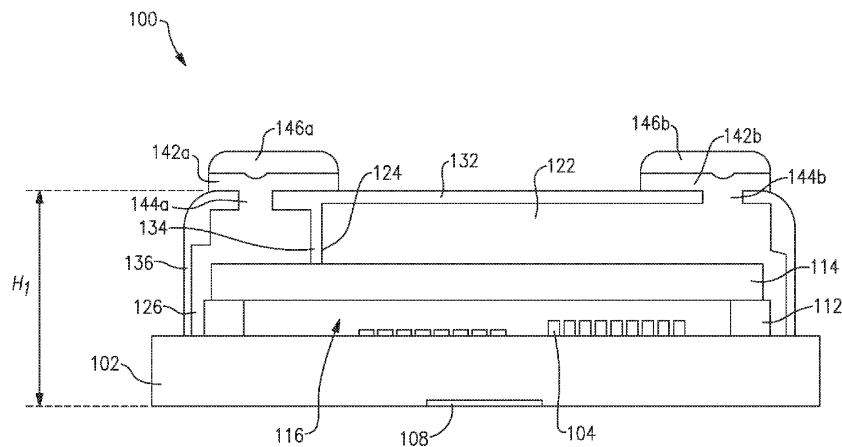


FIG. 1

(57) **Abstract:** Packaged surface acoustic wave devices, and methods of making the same are provided. The packaged surface acoustic wave devices are relatively thin and can have a height of less than 220 micrometers. The packaged surface acoustic wave device includes a photosensitive resin over a conductive structure which may be formed by a plating process. The conductive structure may overlie a cavity-defining structure encapsulating a surface acoustic wave device, the cavity-defining structure including walls and a roof. The photosensitive resin can include a phenol resin. The photosensitive resin can be relatively thin. Edge portions of a piezoelectric substrate can be free from the photosensitive resin. Laser-marked packaged surface acoustic wave devices and methods of making the same are also provided. The opposite side of a piezoelectric substrate supporting a package surface acoustic wave device can be directly marked using a laser. By directly marking the piezoelectric substrate itself, the use of a separate marking film can be avoided, making the packaged surface acoustic wave device thinner.

[Continued on next page]

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